

Tuesday June 18th

(World Trade Center – Grenoble, France)



Funded by
the European Union

The project is supported by the CHIPS-JU and its members

14h00- 14h15 PACK4EU Final workshop - Opening by Jean-Marc YANNOU (Auditorium)

14h15- 14h45 **Keynote on “The Reindustrialization of Semiconductor Packaging in Europe- PACK4EU Final Recommendations”**, Renaud de LANGLADE (EPoSS and Chips JU, Board member)

14h45 – 15h15: Keynote on “Semiconductor and packaging landscape in EU amidst a global geopolitical context”, Emilie JOLIVET (Director, More Moore Business Line) and Stefan CHITORAGA (Technology and Market Analyst, Packaging & Assembly) **YOLE Group**

15h15 – 15h40 Coffee break (Exhibition Hall) sponsored by PACK4EU

15h40 – 16h40 **Pannel session- “Discussions on the PACK4EU Final recommendations”- Part 1**

Chairman, Jean-Marc YANNOU, **ASE Europe**

Panellists from the Semiconductor Value Chain.

- Laurent HERARD - **STMicroelectronics**
- Jean-René LEQUEPEYS - **CEA**
- Didier FLORIOT - **Thales**
- Mario IBRAHIM - **AT&S**
- Fabien CORSAT - **ITEN**

16h40 – 17h00 **Pannel session- “Discussions on the PACK4EU Final recommendations”- Part 2**

Panellists from EU policy makers and Public Authorities.

- Europe : Pack4EU, Eric FRIBOURG-BLANC, Chips Joint Undertaking
- France PA, BPI or DGE tbc
- Regional PA: Rhone Alpes tbc.

17h00 – 17h50 **Open discussions with Audience**

17h50 – 18h00 Closing remarks by Jean-Marc YANNOU (Auditorium)

18h00 -19h15 PACK4EU Cocktail with MiNaPAD exhibitors

REGISTRATION MANDATORY & Free of Charge

via IMAPS website ([MiNaPAD Forum 2024 – IMAPS France \(imapseurope.org\)](https://www.imapseurope.org))

Or

via email : imaps.france@orange.fr



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